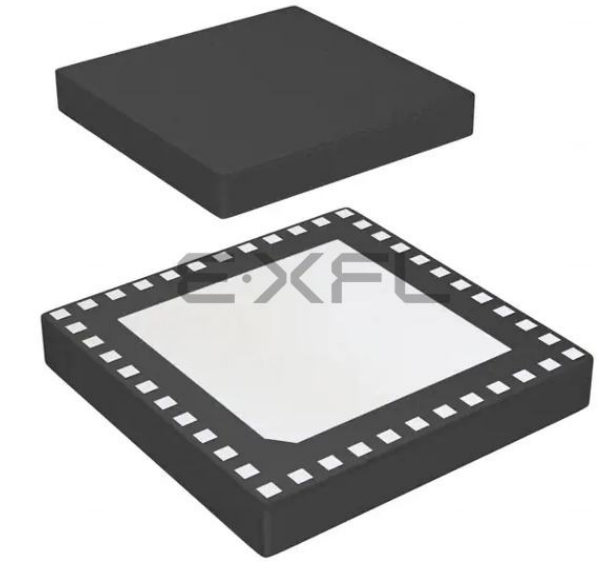

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VFTLA Exposed Pad
Supplier Device Package	44-VTLA (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx120f032d-i-tl

3.2 Architecture Overview

The MIPS32 M4K processor core contains several logic blocks working together in parallel, providing an efficient high-performance computing engine. The following blocks are included with the core:

- Execution Unit
- Multiply/Divide Unit (MDU)
- System Control Coprocessor (CP0)
- Fixed Mapping Translation (FMT)
- Dual Internal Bus interfaces
- Power Management
- MIPS16e® Support
- Enhanced JTAG (EJTAG) Controller

3.2.1 EXECUTION UNIT

The MIPS32 M4K processor core execution unit implements a load/store architecture with single-cycle ALU operations (logical, shift, add, subtract) and an autonomous multiply/divide unit. The core contains thirty-two 32-bit General Purpose Registers (GPRs) used for integer operations and address calculation. The register file consists of two read ports and one write port and is fully bypassed to minimize operation latency in the pipeline.

The execution unit includes:

- 32-bit adder used for calculating the data address
- Address unit for calculating the next instruction address
- Logic for branch determination and branch target address calculation
- Load aligner
- Bypass multiplexers used to avoid stalls when executing instruction streams where data producing instructions are followed closely by consumers of their results
- Leading Zero/One detect unit for implementing the `CLZ` and `CLO` instructions
- Arithmetic Logic Unit (ALU) for performing bitwise logical operations
- Shifter and store aligner

3.2.2 MULTIPLY/DIVIDE UNIT (MDU)

The MIPS32 M4K processor core includes a Multiply/Divide Unit (MDU) that contains a separate pipeline for multiply and divide operations. This pipeline operates in parallel with the Integer Unit (IU) pipeline and does not stall when the IU pipeline stalls. This allows MDU operations to be partially masked by system stalls and/or other integer unit instructions.

The high-performance MDU consists of a 32x16 booth recoded multiplier, result/accumulation registers (HI and LO), a divide state machine, and the necessary multiplexers and control logic. The first number shown ('32' of 32x16) represents the *rs* operand. The second number ('16' of 32x16) represents the *rt* operand. The PIC32 core only checks the value of the latter (*rt)* operand to determine how many times the operation must pass through the multiplier. The 16x16 and 32x16 operations pass through the multiplier once. A 32x32 operation passes through the multiplier twice.

The MDU supports execution of one 16x16 or 32x16 multiply operation every clock cycle; 32x32 multiply operations can be issued every other clock cycle. Appropriate interlocks are implemented to stall the issuance of back-to-back 32x32 multiply operations. The multiply operand size is automatically determined by logic built into the MDU.

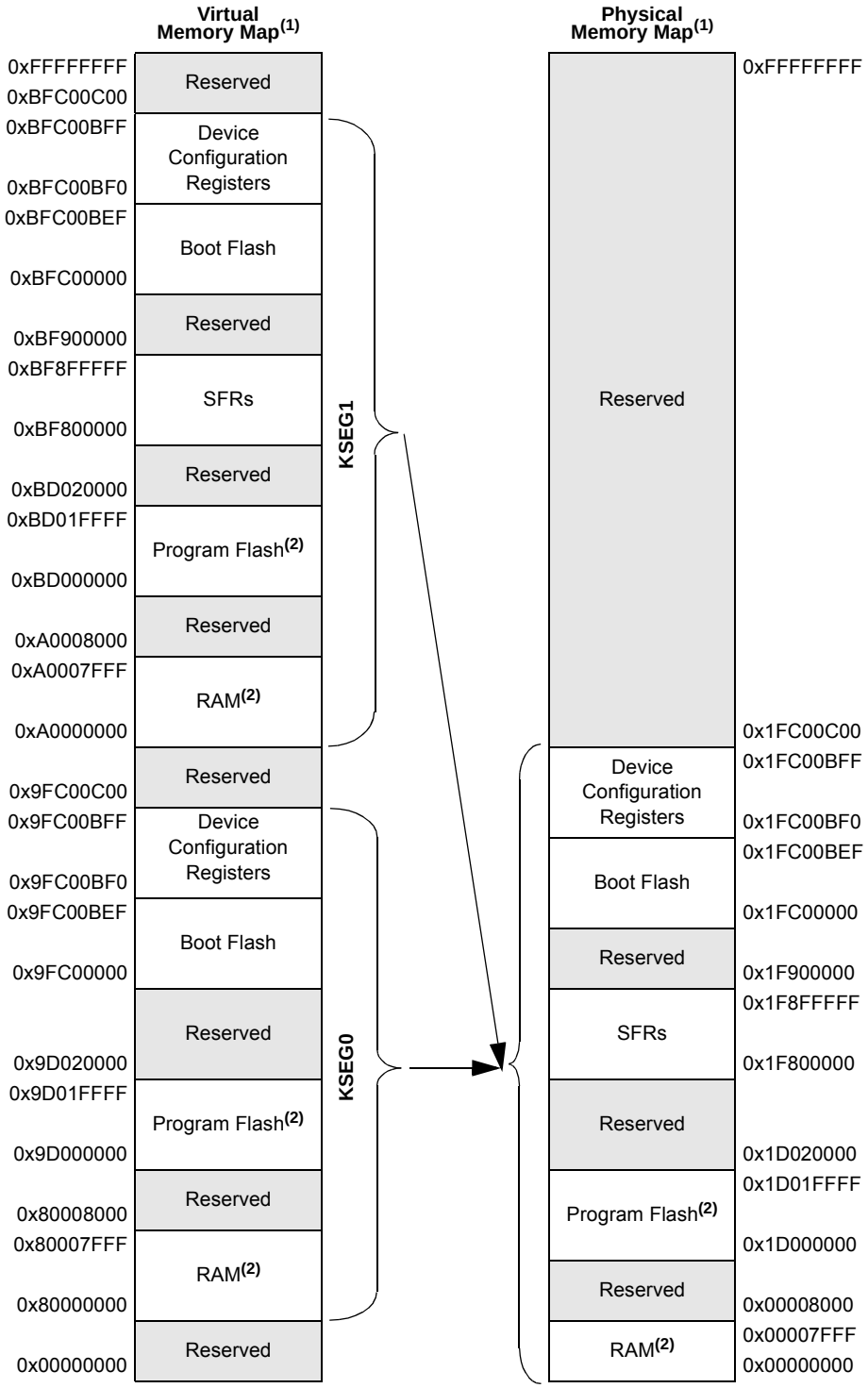
Divide operations are implemented with a simple 1 bit per clock iterative algorithm. An early-in detection checks the sign extension of the dividend (*rs*) operand. If *rs* is 8 bits wide, 23 iterations are skipped. For a 16-bit wide *rs*, 15 iterations are skipped and for a 24-bit wide *rs*, 7 iterations are skipped. Any attempt to issue a subsequent `MDU` instruction while a divide is still active causes an IU pipeline stall until the divide operation is completed.

Table 3-1 lists the repeat rate (peak issue rate of cycles until the operation can be reissued) and latency (number of cycles until a result is available) for the PIC32 core multiply and divide instructions. The approximate latency and repeat rates are listed in terms of pipeline clocks.

TABLE 3-1: MIPS32® M4K® PROCESSOR CORE HIGH-PERFORMANCE INTEGER MULTIPLY/DIVIDE UNIT LATENCIES AND REPEAT RATES

Opcode	Operand Size (mul *rt*) (div *rs*)	Latency	Repeat Rate
`MULT/MULTU, MADD/MADDU, MSUB/MSUBU`	16 bits	1	1
	32 bits	2	2
`MUL`	16 bits	2	1
	32 bits	3	2
`DIV/DIVU`	8 bits	12	11
	16 bits	19	18
	24 bits	26	25
	32 bits	33	32

FIGURE 4-4: MEMORY MAP ON RESET FOR PIC32MX150/250 DEVICES (32 KB RAM, 128 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

REGISTER 5-2: NVMKEY: PROGRAMMING UNLOCK REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
	NVMKEY<31:24>							
23:16	W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
	NVMKEY<23:16>							
15:8	W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
	NVMKEY<15:8>							
7:0	W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
	NVMKEY<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **NVMKEY<31:0>:** Unlock Register bits
These bits are write-only, and read as '0' on any read

Note: This register is used as part of the unlock sequence to prevent inadvertent writes to the PFM.

REGISTER 5-3: NVMADDR: FLASH ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMADDR<31:24>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMADDR<23:16>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMADDR<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMADDR<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **NVMADDR<31:0>:** Flash Address bits
Bulk/Chip/PFM Erase: Address is ignored.
Page Erase: Address identifies the page to erase.
Row Program: Address identifies the row to program.
Word Program: Address identifies the word to program.

REGISTER 8-2: OSCTUN: FRC TUNING REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	R-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	R-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	TUN<5:0>(1)					

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-6 **Unimplemented:** Read as '0'

bit 5-0 **TUN<5:0>:** FRC Oscillator Tuning bits(1)

100000 = Center frequency -12.5%
100001 =
•
•
•
111111 =
000000 = Center frequency. Oscillator runs at minimal frequency (8 MHz)
000001 =
•
•
•
011110 =
011111 = Center frequency +12.5%

Note 1: OSCTUN functionality has been provided to help customers compensate for temperature effects on the FRC frequency over a wide range of temperatures. The tuning step size is an approximation, and is neither characterized, nor tested.

Note: Writes to this register require an unlock sequence. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

9.1 DMA Control Registers

TABLE 9-1: DMA GLOBAL REGISTER MAP

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3000	DMACON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	—	SUSPEND	DMABUSY	—	—	—	—	—	—	—	—	—	—	—	0000
3010	DMASTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RDWR	DMACH<2:0>(2)			0000
3020	DMAADDR	31:16	DMAADDR<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

TABLE 9-2: DMA CRC REGISTER MAP

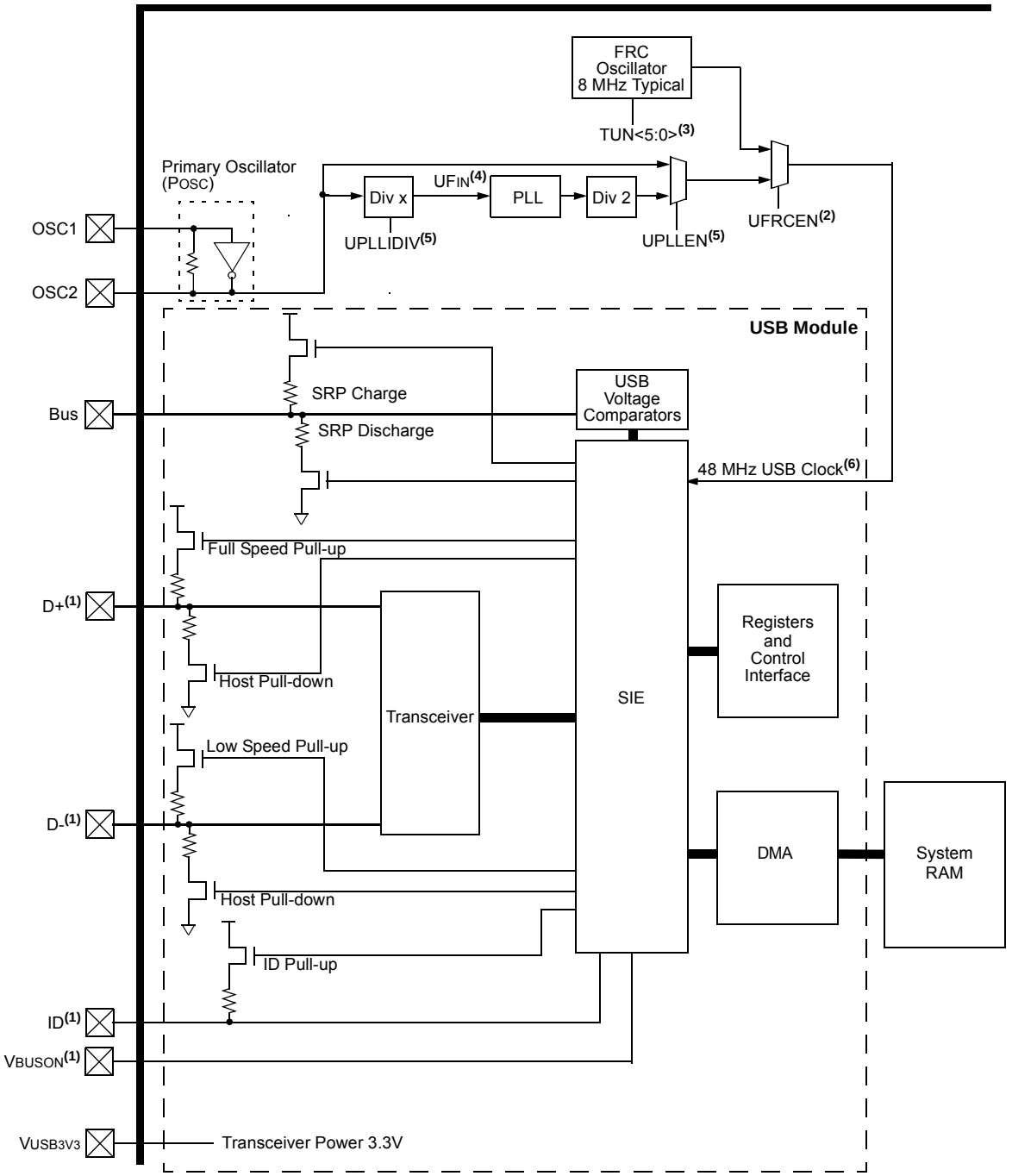
Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3030	DCRCCON	31:16	—	—	BYTO<1:0>		WBO	—	—	BITO	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	PLEN<4:0>					CRCEN	CRCAPP	CRCTYP	—	—	CRCCH<2:0>			0000
3040	DCRCDATA	31:16	DCRCDATA<31:0>																0000
		15:0																	0000
3050	DCRCXOR	31:16	DCRCXOR<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

NOTES:

FIGURE 10-1: PIC32MX1XX/2XX 28/36/44-PIN FAMILY FAMILY USB INTERFACE DIAGRAM



Note 1: Pins can be used as digital input/output when USB is not enabled.
2: This bit field is contained in the OSCCON register.
3: This bit field is contained in the OSCTRM register.
4: USB PLL UFIN requirements: 4 MHz.
5: This bit field is contained in the DEVCFG2 register.
6: A 48 MHz clock is required for proper USB operation.

REGISTER 10-8: U1EIR: USB ERROR INTERRUPT STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS
	BTSEF	BMXEF	DMAEF(1)	BTOEF(2)	DFN8EF	CRC16EF	CRC5EF(4) / EOFEF(3,5)	PIDEF

Legend:	WC = Write '1' to clear	HS = Hardware Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **BTSEF:** Bit Stuff Error Flag bit
- 1 = Packet rejected due to bit stuff error
- 0 = Packet accepted

bit 6 **BMXEF:** Bus Matrix Error Flag bit
- 1 = The base address, of the Buffer Descriptor Table, or the address of an individual buffer pointed to by a Buffer Descriptor Table entry, is invalid.
- 0 = No address error

bit 5 **DMAEF:** DMA Error Flag bit(1)
- 1 = USB DMA error condition detected
- 0 = No DMA error

bit 4 **BTOEF:** Bus Turnaround Time-Out Error Flag bit(2)
- 1 = Bus turnaround time-out has occurred
- 0 = No bus turnaround time-out

bit 3 **DFN8EF:** Data Field Size Error Flag bit
- 1 = Data field received is not an integral number of bytes
- 0 = Data field received is an integral number of bytes

bit 2 **CRC16EF:** CRC16 Failure Flag bit
- 1 = Data packet rejected due to CRC16 error
- 0 = Data packet accepted

Note 1: This type of error occurs when the module's request for the DMA bus is not granted in time to service the module's demand for memory, resulting in an overflow or underflow condition, and/or the allocated buffer size is not sufficient to store the received data packet causing it to be truncated.

2: This type of error occurs when more than 16-bit-times of Idle from the previous End-of-Packet (EOP) has elapsed.

3: This type of error occurs when the module is transmitting or receiving data and the SOF counter has reached zero.

4: Device mode.

5: Host mode.

15.1 Input Capture Control Registers

TABLE 15-1: INPUT CAPTURE 1-INPUT CAPTURE 5 REGISTER MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
2000	IC1CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2010	IC1BUF	31:16	IC1BUF<31:0>																xxxx
		15:0																	xxxx
2200	IC2CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2210	IC2BUF	31:16	IC2BUF<31:0>																xxxx
		15:0																	xxxx
2400	IC3CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2410	IC3BUF	31:16	IC3BUF<31:0>																xxxx
		15:0																	xxxx
2600	IC4CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2610	IC4BUF	31:16	IC4BUF<31:0>																xxxx
		15:0																	xxxx
2800	IC5CON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	FEDGE	C32	ICTMR	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
2810	IC5BUF	31:16	IC5BUF<31:0>																xxxx
		15:0																	xxxx

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

19.1 UART Control Registers

TABLE 19-1: UART1 AND UART2 REGISTER MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6000	U1MODE(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	IREN	RTSMD	—	UEN<1:0>		WAKE	LPBACK	ABAUD	RXINV	BRGH	PDSEL<1:0>		STSEL	0000
6010	U1STA(1)	31:16	—	—	—	—	—	—	—	ADM_EN	ADDR<7:0>								0000
		15:0	UTXISEL<1:0>		UTXINV	URXEN	UTXBRK	UTXEN	UTXBF	TRMT	URXISEL<1:0>		ADDEN	RIDLE	PERR	FERR	OERR	URXDA	0110
6020	U1TXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	Transmit Register									0000
6030	U1RXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	Receive Register									0000
6040	U1BRG(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	Baud Rate Generator Prescaler																0000
6200	U2MODE(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	IREN	RTSMD	—	UEN<1:0>		WAKE	LPBACK	ABAUD	RXINV	BRGH	PDSEL<1:0>		STSEL	0000
6210	U2STA(1)	31:16	—	—	—	—	—	—	—	ADM_EN	ADDR<7:0>								0000
		15:0	UTXISEL<1:0>		UTXINV	URXEN	UTXBRK	UTXEN	UTXBF	TRMT	URXISEL<1:0>		ADDEN	RIDLE	PERR	FERR	OERR	URXDA	0110
6220	U2TXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	Transmit Register									0000
6230	U2RXREG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	Receive Register									0000
6240	U2BRG(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	Baud Rate Generator Prescaler																0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

REGISTER 21-2: RTCALRM: RTC ALARM CONTROL REGISTER (CONTINUED)

bit 7-0 **ARPT<7:0>:** Alarm Repeat Counter Value bits(2)

11111111 = Alarm will trigger 256 times
•
•
•
00000000 = Alarm will trigger one time
The counter decrements on any alarm event. The counter only rolls over from 0x00 to 0xFF if CHIME = 1.

Note 1: Hardware clears the ALRMEN bit anytime the alarm event occurs, when ARPT<7:0> = 00 and CHIME = 0.

2: This field should not be written when the RTCC ON bit = '1' (RTCCON<15>) and ALRMSYNC = 1.

3: This assumes a CPU read will execute in less than 32 PBCLKs.

Note:	This register is reset only on a Power-on Reset (POR).

REGISTER 21-4: RTCDATE: RTC DATE VALUE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	YEAR10<3:0>				YEAR01<3:0>			
23:16	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	—	—	—	MONTH10	MONTH01<3:0>			
15:8	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	—	—	DAY10<1:0>		DAY01<3:0>			
7:0	U-0	U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
	—	—	—	—	—	WDAY01<2:0>		

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-28 **YEAR10<3:0>:** Binary-Coded Decimal Value of Years bits, 10s place digit; contains a value from 0 to 9

bit 27-24 **YEAR01<3:0>:** Binary-Coded Decimal Value of Years bits, 1s place digit; contains a value from 0 to 9

bit 23-21 **Unimplemented:** Read as '0'

bit 20 **MONTH10:** Binary-Coded Decimal Value of Months bits, 10s place digit; contains a value of 0 or 1

bit 19-16 **MONTH01<3:0>:** Binary-Coded Decimal Value of Months bits, 1s place digit; contains a value from 0 to 9

bit 15-14 **Unimplemented:** Read as '0'

bit 13-12 **DAY10<1:0>:** Binary-Coded Decimal Value of Days bits, 10s place digit; contains a value of 0 to 3

bit 11-8 **DAY01<3:0>:** Binary-Coded Decimal Value of Days bits, 1s place digit; contains a value from 0 to 9

bit 7-3 **Unimplemented:** Read as '0'

bit 2-0 **WDAY01<2:0>:** Binary-Coded Decimal Value of Weekdays bits; contains a value from 0 to 6

Note: This register is only writable when RTCWREN = 1 (RTCCON<3>).

22.0 10-BIT ANALOG-TO-DIGITAL CONVERTER (ADC)

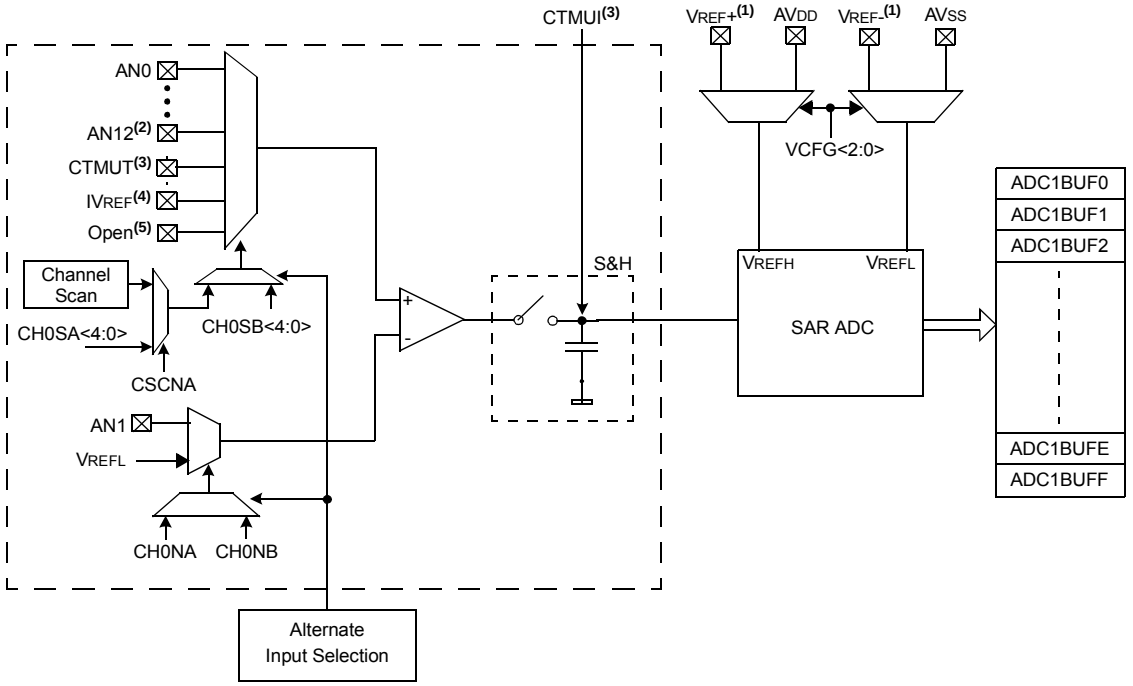
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS60001104), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The 10-bit Analog-to-Digital Converter (ADC) includes the following features:

- Successive Approximation Register (SAR) conversion
- Up to 1 Msps conversion speed
- Up to 13 analog input pins
- External voltage reference input pins
- One unipolar, differential Sample and Hold Amplifier (SHA)
- Automatic Channel Scan mode
- Selectable conversion trigger source
- 16-word conversion result buffer
- Selectable buffer fill modes
- Eight conversion result format options
- Operation during Sleep and Idle modes

A block diagram of the 10-bit ADC is illustrated in Figure 22-1. Figure 22-2 illustrates a block diagram of the ADC conversion clock period. The 10-bit ADC has up to 13 analog input pins, designated AN0-AN12. In addition, there are two analog input pins for external voltage reference connections. These voltage reference inputs may be shared with other analog input pins and may be common to other analog module references.

FIGURE 22-1: ADC1 MODULE BLOCK DIAGRAM



Note 1: VREF+ and VREF- inputs can be multiplexed with other analog inputs.

2: AN8 is only available on 44-pin devices. AN6, AN7, and AN12 are not available on 28-pin devices.

3: Connected to the CTMU module. See **Section 25.0 "Charge Time Measurement Unit (CTMU)"** for more information.

4: Internal precision voltage reference (1.2V).

5: This selection is only used with CTMU capacitive and time measurement.

REGISTER 23-1: CMXCON: COMPARATOR CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	R-0
	ON(1)	COE	CPOL(2)	—	—	—	—	COUT
7:0	R/W-1	R/W-1	U-0	R/W-0	U-0	U-0	R/W-1	R/W-1
	EVPOL<1:0>		—	CREF	—	—	CCH<1:0>	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Comparator ON bit(1)
- 1 = Module is enabled. Setting this bit does not affect the other bits in this register
- 0 = Module is disabled and does not consume current. Clearing this bit does not affect the other bits in this register

bit 14 **COE:** Comparator Output Enable bit
- 1 = Comparator output is driven on the output CxOUT pin
- 0 = Comparator output is not driven on the output CxOUT pin

bit 13 **CPOL:** Comparator Output Inversion bit(2)
- 1 = Output is inverted
- 0 = Output is not inverted

bit 12-9 **Unimplemented:** Read as '0'

bit 8 **COUT:** Comparator Output bit
- 1 = Output of the Comparator is a '1'
- 0 = Output of the Comparator is a '0'

bit 7-6 **EVPOL<1:0>:** Interrupt Event Polarity Select bits
- 11 = Comparator interrupt is generated on a low-to-high or high-to-low transition of the comparator output
- 10 = Comparator interrupt is generated on a high-to-low transition of the comparator output
- 01 = Comparator interrupt is generated on a low-to-high transition of the comparator output
- 00 = Comparator interrupt generation is disabled

bit 5 **Unimplemented:** Read as '0'

bit 4 **CREF:** Comparator Positive Input Configure bit
- 1 = Comparator non-inverting input is connected to the internal CVREF
- 0 = Comparator non-inverting input is connected to the CXINA pin

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **CCH<1:0>:** Comparator Negative Input Select bits for Comparator
- 11 = Comparator inverting input is connected to the IVREF
- 10 = Comparator inverting input is connected to the CxIND pin
- 01 = Comparator inverting input is connected to the CxINC pin
- 00 = Comparator inverting input is connected to the CxINB pin

Note 1: When using the 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: Setting this bit will invert the signal to the comparator interrupt generator as well. This will result in an interrupt being generated on the opposite edge from the one selected by EVPOL<1:0>.

TABLE 30-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp		
Param. No.	**Typical(2)**	**Max.**	**Units**	**Conditions**	
Power-Down Current (I_{PD}) (Notes 1, 5)					
DC40k	44	70	μA	-40°C	Base Power-Down Current
DC40l	44	70	μA	+25°C	
DC40n	168	259	μA	+85°C	
DC40m	335	536	μA	+105ºC	
Module Differential Current					
DC41e	5	20	μA	3.6V	Watchdog Timer Current: ΔI_{WDT} **(Note 3)**
DC42e	23	50	μA	3.6V	RTCC + Timer1 w/32 kHz Crystal: ΔI_{RTCC} **(Note 3)**
DC43d	1000	1100	μA	3.6V	ADC: ΔI_{ADC} **(Notes 3,4)**

Note 1: The test conditions for I_{PD} current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Sleep mode, and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is set
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}
- RTCC and JTAG are disabled

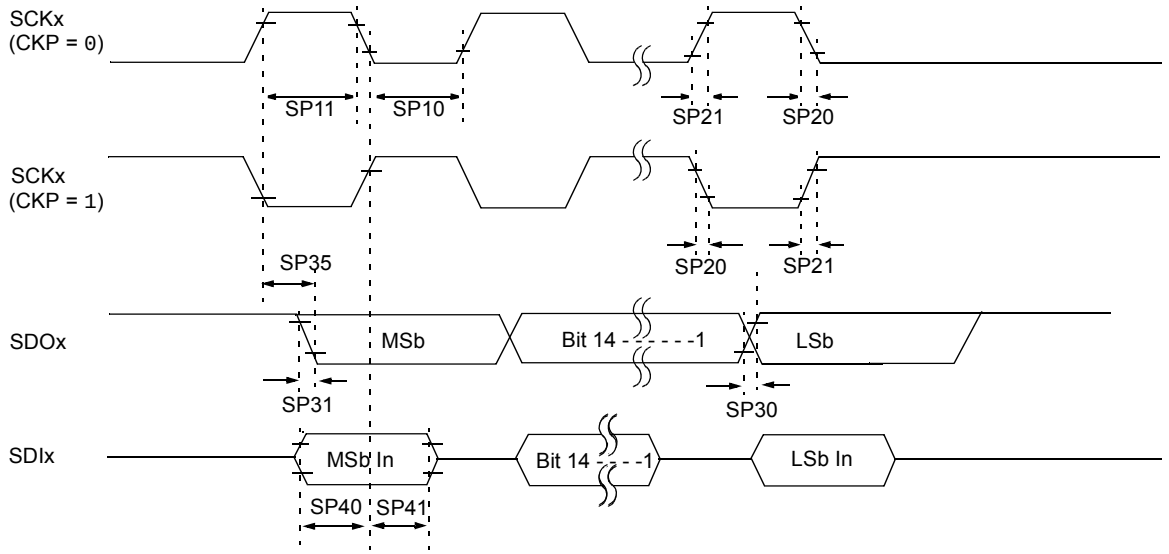
2: Data in the "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

5: I_{PD} electrical characteristics for devices with 256 KB Flash are only provided as Preliminary information.

FIGURE 30-10: SPIx MODULE MASTER MODE (CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-28: SPIx MASTER MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
SP10	TscL	SCKx Output Low Time **(Note 3)**	TSCK/2	—	—	ns	—
SP11	TscH	SCKx Output High Time **(Note 3)**	TSCK/2	—	—	ns	—
SP20	TscF	SCKx Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP21	TscR	SCKx Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP30	TdoF	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 50 ns. Therefore, the clock generated in Master mode must not violate this specification.

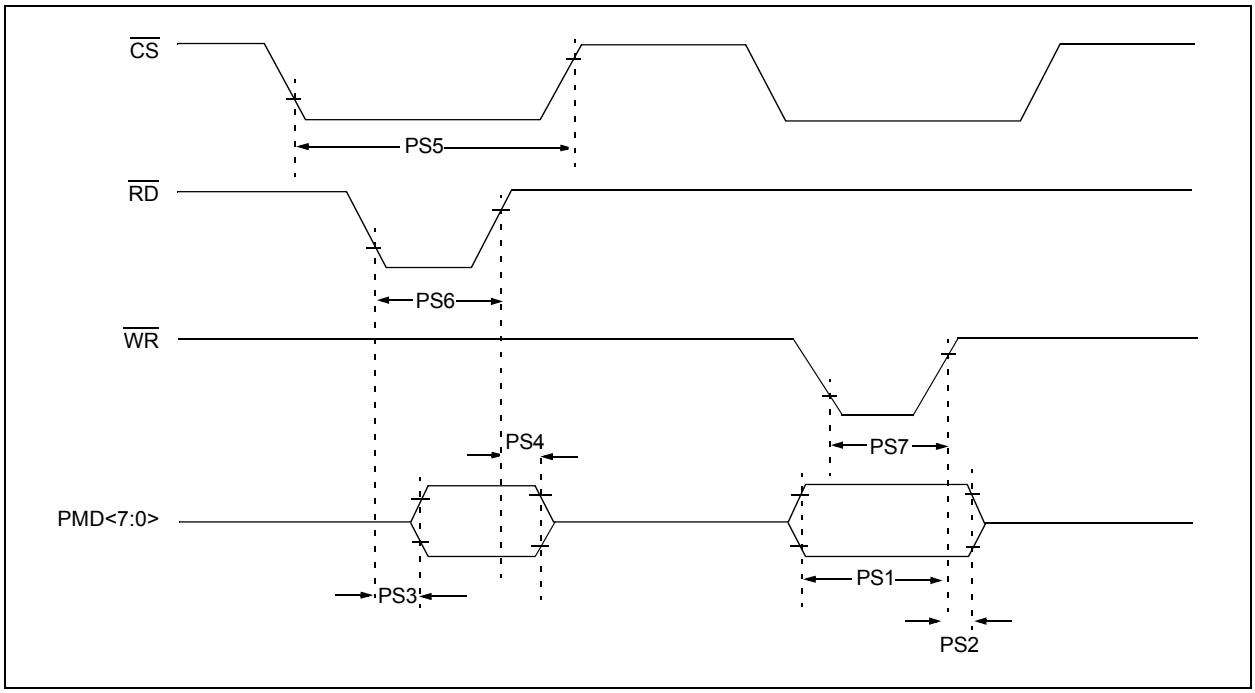
4: Assumes 50 pF load on all SPIx pins.

TABLE 30-33: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE) (CONTINUED)

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.**	**Max.**	**Units**	**Conditions**
IS34	THD:STO	Stop Condition Hold Time	100 kHz mode	4000	—	ns	—
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	250		ns	
IS40	TAA:SCL	Output Valid from Clock	100 kHz mode	0	3500	ns	—
			400 kHz mode	0	1000	ns	
			1 MHz mode **(Note 1)**	0	350	ns	
IS45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	The amount of time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode **(Note 1)**	0.5	—	µs	
IS50	CB	Bus Capacitive Loading		—	400	pF	—

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

FIGURE 30-20: PARALLEL SLAVE PORT TIMING

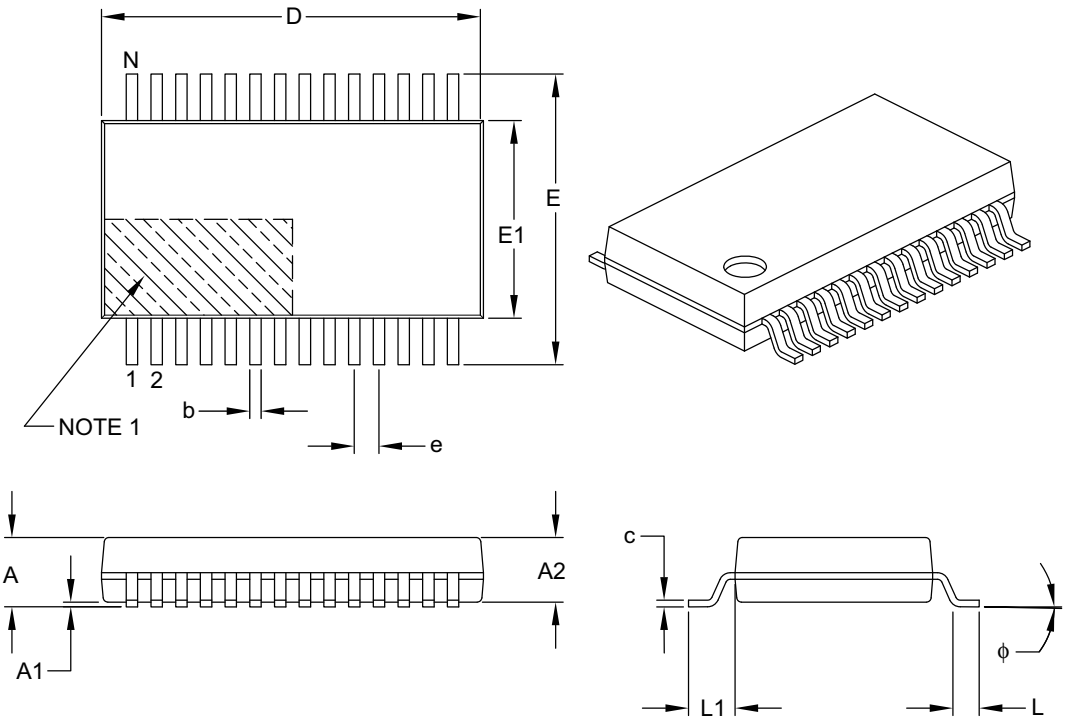


33.2 Package Details

This section provides the technical details of the packages.

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

Revision F (February 2014)

This revision includes the addition of the following devices:

- PIC32MX170F256B
- PIC32MX270F256B
- PIC32MX170F256D
- PIC32MX270F256D

In addition, this revision includes the following major changes as described in Table A-5, as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-5: MAJOR SECTION UPDATES

Section	Update Description
32-bit Microcontrollers (up to 256 KB Flash and 64 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog	Added new devices to the family features (see Table 1 and Table 2). Updated pin diagrams to include new devices (see **"Pin Diagrams"**).
1.0 "Device Overview"	Added Note 3 reference to the following pin names: VBUS, VUSB3V3, VBUSON, D+, D-, and USBID.
2.0 "Guidelines for Getting Started with 32-bit MCUs"	Replaced Figure 2-1: Recommended Minimum Connection. Updated Figure 2-2: $\overline{MCLR}$ Pin Connections. Added **2.9 "Sosc Design Recommendation"**.
4.0 "Memory Organization"	Added memory tables for devices with 64 KB RAM (see Table 4-4 through Table 4-5). Changed the Virtual Addresses for all registers and updated the PWP bits in the DEVCFG: Device Configuration Word Summary (see Table 4-17). Updated the ODCA, ODCB, and ODCC port registers (see Table 4-19, Table 4-20, and Table 4-21). The RTCTIME, RTCDATE, ALRMTIME, and ALRMDATE registers were updated (see Table 4-25). Added Data Ram Size value for 64 KB RAM devices (see Register 4-5). Added Program Flash Size value for 256 KB Flash devices (see Register 4-5).
12.0 "Timer1"	The Timer1 block diagram was updated to include the 16-bit data bus (see Figure 12-1).
13.0 "Timer2/3, Timer4/5"	The Timer2-Timer5 block diagram (16-bit) was updated to include the 16-bit data bus (see Figure 13-1). The Timer2/3, Timer4/5 block diagram (32-bit) was updated to include the 32-bit data bus (see Figure 13-1).
19.0 "Parallel Master Port (PMP)"	The CSF<1:0> bit value definitions for '00' and '01' were updated (see Register 19-1). Bit 14 in the Parallel Port Address register (PMADDR) was updated (see Register 19-3).
20.0 "Real-Time Clock and Calendar (RTCC)"	The following registers were updated: RTCTIME (see Register 20-3) RTCDATE (see Register 20-4) ALRMTIME (see Register 20-5) ALRMDATE (see Register 20-6)
26.0 "Special Features"	Updated the PWP bits (see Register 26-1).
29.0 "Electrical Characteristics"	Added parameters DO50 and DO50a to the Capacitive Loading Requirements on Output Pins (see Table 29-14). Added Note 5 to the IDD DC Characteristics (see Table 29-5). Added Note 4 to the IIDLE DC Characteristics (see Table 29-6). Added Note 5 to the IPD DC Characteristics (see Table 29-7). Updated the conditions for parameters USB321 (VOL) and USB322 (VOH) in the OTG Electrical Specifications (see Table 29-38).
Product Identification System	Added 40 MHz speed information.